



Material Content Data Sheet



Halogen-Free

Sales Product Name	BSC019N06NS	Issued	25. June 2021
MA#	MA005561377		
Package	PG-TDSON-8-26	Weight*	114.91 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.188	1.03	1.03	10337	10337
leadframe	inorganic material	phosphorus	7723-14-0	0.016	0.01		135	
	non noble metal	iron	7439-89-6	0.052	0.05		451	
	non noble metal	copper	7440-50-8	51.740	45.04	45.10	450258	450844
wire	noble metal	gold	7440-57-5	0.045	0.04	0.04	392	392
encapsulation	organic material	carbon black	1333-86-4	0.082	0.07		710	
	plastics	epoxy resin	-	6.450	5.61		56125	
	inorganic material	silicondioxide	60676-86-0	34.289	29.84	35.52	298387	355222
leadfinish	non noble metal	tin	7440-31-5	1.392	1.21	1.21	12110	12110
plating	noble metal	silver	7440-22-4	0.194	0.17	0.17	1687	1687
solder	non noble metal	tin	7440-31-5	0.034	0.03		292	
	noble metal	silver	7440-22-4	0.042	0.04		365	
	non noble metal	lead	7439-92-1	1.602	1.39	1.46	13945	14602
heat sink clip	inorganic material	phosphorus	7723-14-0	0.005			45	
	non noble metal	iron	7439-89-6	0.017	0.01		149	
	noble metal	silver	7440-22-4	0.635	0.55		5530	
	non noble metal	copper	7440-50-8	17.131	14.91	15.47	149082	154806
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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